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Applicants: Lakin et al.

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STATEMENT UNDER 37 CFR § 3.73(b)

TriQuint Semiconductor, Inc., a corporation, states that it is the assignee of the entire right, title, and interest in the patent application/patent identified above by virtue of a chain of title from the inventors, to the current assignee of the patent application/patent identified above, as follows:

1. From: Kenneth Meade Lakin, Ralph Edward Rose, and Kevin Thomas McCarron
To: TFR Technologies, Inc.
The document was recorded in the United States Patent and Trademark Office at Reel 009325, Frame 0921, recorded on July 14, 1998.
2. From: TFR Technologies, Inc.
To: TriQuint Semiconductor, Inc.
The document was recorded in the United States Patent and Trademark Office at Reel 016844, Frame 0147, recorded on July 20, 2005.

The undersigned is authorized to sign this Power of Attorney by Assignee on behalf of the assignee.

Executed at Hillsboro, OR on the 4th day of June, 2010.
(city and state)

TriQuint Semiconductor, Inc.

By

Name: Steve Buhaly

Title: Vice President and CFO